



## SNx4HC05 Hex Inverters With Open-Drain Outputs

### 1 Features

- Wide Operating Voltage Range of 2 V to 6 V
- Outputs can Drive up to 10 LSTTL Loads
- Low-Power Consumption, 20- $\mu$ A Maximum ICC
- Typical  $t_{pd} = 8$  ns
- $\pm 4$ -mA Output Drive at 5 V
- Low Input Current of 1- $\mu$ A Maximum

### 2 Applications

- Mice
- Printers
- AC Inverter Drives
- UPS
- AC Servo Drives
- Other Motor Drives

### 3 Description

The SNx4HC05 devices contain six independent inverters. They perform the Boolean function  $Y = \bar{A}$  in positive logic. The open-drain outputs require pullup resistors to perform correctly. They may be connected to other open-drain outputs to implement active-low wired-OR or active-high wired-AND functions.

#### Device Information<sup>(1)</sup>

| PART NUMBER | PACKAGE    | BODY SIZE (NOM)           |
|-------------|------------|---------------------------|
| SN74HC05    | PDIP (14)  | 19.30 mm $\times$ 6.40 mm |
|             | SOIC (14)  | 8.65 mm $\times$ 3.91 mm  |
|             | SOP (14)   | 10.30 mm $\times$ 5.30 mm |
|             | TSSOP (14) | 5.00 mm $\times$ 4.40 mm  |

(1) For all available packages, see the orderable addendum at the end of the data sheet.

#### Logic Diagram (Positive Logic)



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## 4 Revision History

### Changes from Revision D (August 2003) to Revision E

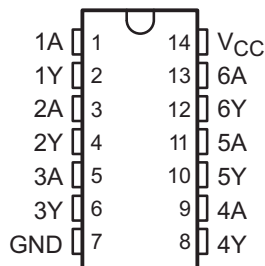
Page

- Added *Pin Configuration and Functions* section, *ESD Ratings* table, *Feature Description* section, *Device Functional Modes*, *Application and Implementation* section, *Power Supply Recommendations* section, *Layout* section, *Device and Documentation Support* section, and *Mechanical, Packaging, and Orderable Information* section ..... **1**

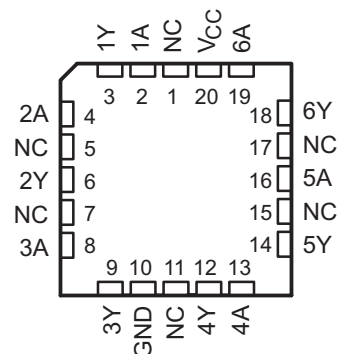
## 5 Pin Configuration and Functions

**SN74HC05: D, N, NS, or PW Package, 14-Pin SOIC, PDIP, SOP, or TSSOP**

**SN54HC05: J or W Package, 19-Pin CDIP or CFP (Top View)**



**SN54HC05: FK Package 20-Pin LCCC (Top View)**



NC – No internal connection

### Pin Functions

| PIN             |     |                     | I/O | DESCRIPTION |
|-----------------|-----|---------------------|-----|-------------|
| NAME            | NO. | LCCC NO.            |     |             |
| 1A              | 1   | 2                   | I   | Input 1     |
| 1Y              | 2   | 3                   | O   | Output 1    |
| 2A              | 3   | 4                   | I   | Input 2     |
| 2Y              | 4   | 6                   | O   | Output 2    |
| 3A              | 5   | 8                   | I   | Input 3     |
| 3Y              | 6   | 9                   | O   | Output 3    |
| GND             | 7   | 10                  | –   | Ground pin  |
| 4A              | 9   | 13                  | I   | Input 4     |
| 4Y              | 8   | 12                  | O   | Output 4    |
| 5A              | 11  | 16                  | I   | Input 5     |
| 5Y              | 10  | 14                  | O   | Output 5    |
| 6A              | 13  | 19                  | I   | Input 6     |
| 6Y              | 12  | 18                  | O   | Output 6    |
| NC              | –   | 1, 5, 7, 11, 15, 17 | –   | No connect  |
| V <sub>CC</sub> | 14  | 20                  | –   | Power pin   |

## 6 Specifications

### 6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) <sup>(1)</sup>

|                  |                                                                                             | MIN  | MAX | UNIT |
|------------------|---------------------------------------------------------------------------------------------|------|-----|------|
| V <sub>CC</sub>  | Supply voltage                                                                              | −0.5 | 7   | V    |
| I <sub>IK</sub>  | Input clamp current, V <sub>I</sub> < 0 or V <sub>I</sub> > V <sub>CC</sub> <sup>(2)</sup>  | −20  | 20  | mA   |
| I <sub>OK</sub>  | Output clamp current, V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> <sup>(2)</sup> | −20  | 20  | mA   |
| I <sub>O</sub>   | Continuous output current, V <sub>O</sub> = 0 to V <sub>CC</sub>                            | −25  | 25  | mA   |
|                  | Continuous current through V <sub>CC</sub> or GND                                           | −50  | 50  | mA   |
| T <sub>stg</sub> | Storage temperature                                                                         | −65  | 150 | °C   |

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

### 6.2 ESD Ratings

|                    |                                                                                              | VALUE | UNIT |
|--------------------|----------------------------------------------------------------------------------------------|-------|------|
| V <sub>(ESD)</sub> | Electrostatic discharge<br>Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup> | ±1000 | V    |

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

### 6.3 Recommended Operating Conditions

See <sup>(1)</sup>

|                 |                                    | MIN                     | NOM  | MAX             | UNIT |
|-----------------|------------------------------------|-------------------------|------|-----------------|------|
| V <sub>CC</sub> | Supply voltage                     | 2                       | 5    | 6               | V    |
| V <sub>IH</sub> | High-level input voltage           | V <sub>CC</sub> = 2 V   | 1.5  |                 | V    |
|                 |                                    | V <sub>CC</sub> = 4.5 V | 3.15 |                 |      |
|                 |                                    | V <sub>CC</sub> = 6 V   | 4.2  |                 |      |
| V <sub>IL</sub> | Low-level input voltage            | V <sub>CC</sub> = 2 V   |      | 0.5             | V    |
|                 |                                    | V <sub>CC</sub> = 4.5 V |      | 1.35            |      |
|                 |                                    | V <sub>CC</sub> = 6 V   |      | 1.8             |      |
| V <sub>I</sub>  | Input voltage                      | 0                       |      | V <sub>CC</sub> | V    |
| V <sub>O</sub>  | Output voltage                     | 0                       |      | V <sub>CC</sub> | V    |
| Δt/Δv           | Input transition rise or fall time | V <sub>CC</sub> = 2 V   |      | 1000            | ns   |
|                 |                                    | V <sub>CC</sub> = 4.5 V |      | 500             |      |
|                 |                                    | V <sub>CC</sub> = 6 V   |      | 400             |      |
| T <sub>A</sub>  | Operating free-air temperature     | SN54HC05                | −55  | 125             | °C   |
|                 |                                    | SN74HC05                | −40  | 125             |      |

- (1) All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, [SCBA004](#).

## 6.4 Thermal Information

| THERMAL METRIC <sup>(1)</sup> |                                              | SN74HC05 |          |          |            | UNIT |
|-------------------------------|----------------------------------------------|----------|----------|----------|------------|------|
|                               |                                              | D (SOIC) | N (PDIP) | NS (SOP) | PW (TSSOP) |      |
|                               |                                              | 14 PINS  | 14 PINS  | 14 PINS  | 14 PINS    |      |
| R <sub>θJA</sub>              | Junction-to-ambient thermal resistance       | 89.1     | 85.9     | 86.4     | 117.1      | °C/W |
| R <sub>θJC(top)</sub>         | Junction-to-case (top) thermal resistance    | 50.6     | 43.8     | 42.4     | 46.1       |      |
| R <sub>θJB</sub>              | Junction-to-board thermal resistance         | 43.3     | 44.6     | 45.1     | 58.7       |      |
| ψ <sub>JT</sub>               | Junction-to-top characterization parameter   | 16.3     | 12       | 11.8     | 4.8        |      |
| ψ <sub>JB</sub>               | Junction-to-board characterization parameter | 43       | 44.2     | 44.7     | 58.1       |      |

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, [SPRA953](#).

## 6.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER       | TEST CONDITIONS                                                                        | V <sub>CC</sub> | T <sub>A</sub> = 25°C |       |      | SN54HC05 |       | SN74HC05<br>–40°C to 85°C |       | SN74HC05<br>–40°C to 125°C |       | UNIT |
|-----------------|----------------------------------------------------------------------------------------|-----------------|-----------------------|-------|------|----------|-------|---------------------------|-------|----------------------------|-------|------|
|                 |                                                                                        |                 | MIN                   | TYP   | MAX  | MIN      | MAX   | MIN                       | MAX   | MIN                        | MAX   |      |
| I <sub>OH</sub> | V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> , V <sub>O</sub> = V <sub>CC</sub> | 6 V             |                       | 0.01  | 0.5  |          | 10    |                           | 5     |                            | 5     | μA   |
| V <sub>OL</sub> | V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub><br>I <sub>OL</sub> = 20 μA         | 2 V             |                       | 0.002 | 0.1  |          | 0.1   |                           | 0.1   |                            | 0.1   | V    |
|                 |                                                                                        | 4.5 V           |                       | 0.001 | 0.1  |          | 0.1   |                           | 0.1   |                            | 0.1   |      |
|                 |                                                                                        | 6 V             |                       | 0.001 | 0.1  |          | 0.1   |                           | 0.1   |                            | 0.1   |      |
|                 |                                                                                        | 4.5 V           |                       | 0.17  | 0.26 |          | 0.4   |                           | 0.33  |                            | 0.33  |      |
|                 | I <sub>OL</sub> = 5.2 mA                                                               | 6 V             |                       | 0.15  | 0.26 |          | 0.4   |                           | 0.33  |                            | 0.33  |      |
| I <sub>I</sub>  | V <sub>I</sub> = V <sub>CC</sub> or 0                                                  | 6 V             |                       | ±0.1  | ±100 |          | ±1000 |                           | ±1000 |                            | ±1000 | nA   |
| I <sub>CC</sub> | V <sub>I</sub> = V <sub>CC</sub> or 0, I <sub>O</sub> = 0                              | 6 V             |                       |       | 2    |          | 40    |                           | 20    |                            | 20    | μA   |
| C <sub>i</sub>  |                                                                                        | 2 to 6 V        |                       | 3     | 10   |          | 10    |                           | 10    |                            | 10    | pF   |

## 6.6 Switching Characteristics

over recommended operating free-air temperature range, C<sub>L</sub> = 50 pF (unless otherwise noted) (see [Figure 3](#))

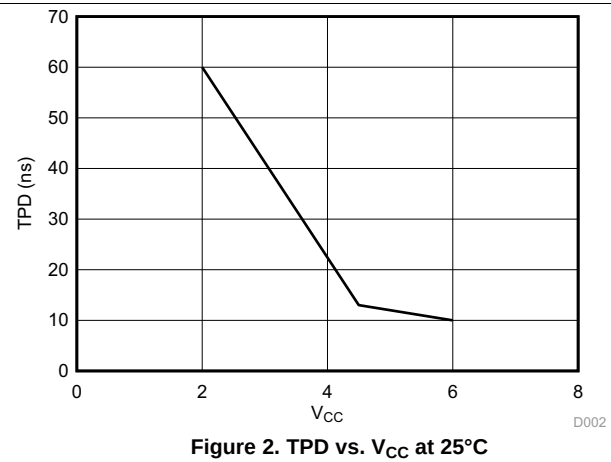
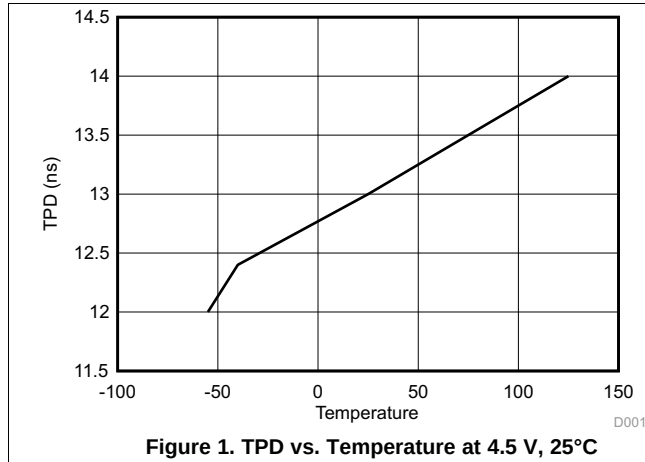
| PARAMETER        | FROM<br>(INPUT) | TO<br>(OUTPUT) | V <sub>CC</sub> | T <sub>A</sub> = 25°C |     |     | SN54HC05 |     | SN74HC05<br>–40°C to 85°C |     | SN74HC05<br>–40°C to 125°C |     | UNIT |
|------------------|-----------------|----------------|-----------------|-----------------------|-----|-----|----------|-----|---------------------------|-----|----------------------------|-----|------|
|                  |                 |                |                 | MIN                   | TYP | MAX | MIN      | MAX | MIN                       | MAX | MIN                        | MAX |      |
| t <sub>PLH</sub> | A               | Y              | 2 V             |                       | 60  | 115 |          | 175 |                           | 145 |                            | 160 | ns   |
|                  |                 |                | 4.5 V           |                       | 13  | 23  |          | 35  |                           | 29  |                            | 31  |      |
|                  |                 |                | 6 V             |                       | 10  | 20  |          | 30  |                           | 25  |                            | 28  |      |
| t <sub>PHL</sub> | A               | Y              | 2 V             |                       | 45  | 85  |          | 130 |                           | 105 |                            | 120 |      |
|                  |                 |                | 4.5 V           |                       | 9   | 17  |          | 26  |                           | 21  |                            | 23  |      |
|                  |                 |                | 6 V             |                       | 8   | 14  |          | 22  |                           | 18  |                            | 21  |      |
| t <sub>f</sub>   |                 | Y              | 2 V             |                       | 38  | 75  |          | 110 |                           | 95  |                            | 110 |      |
|                  |                 |                | 4.5 V           |                       | 8   | 15  |          | 22  |                           | 19  |                            | 22  |      |
|                  |                 |                | 6 V             |                       | 6   | 13  |          | 19  |                           | 16  |                            | 19  |      |

## 6.7 Operating Characteristics

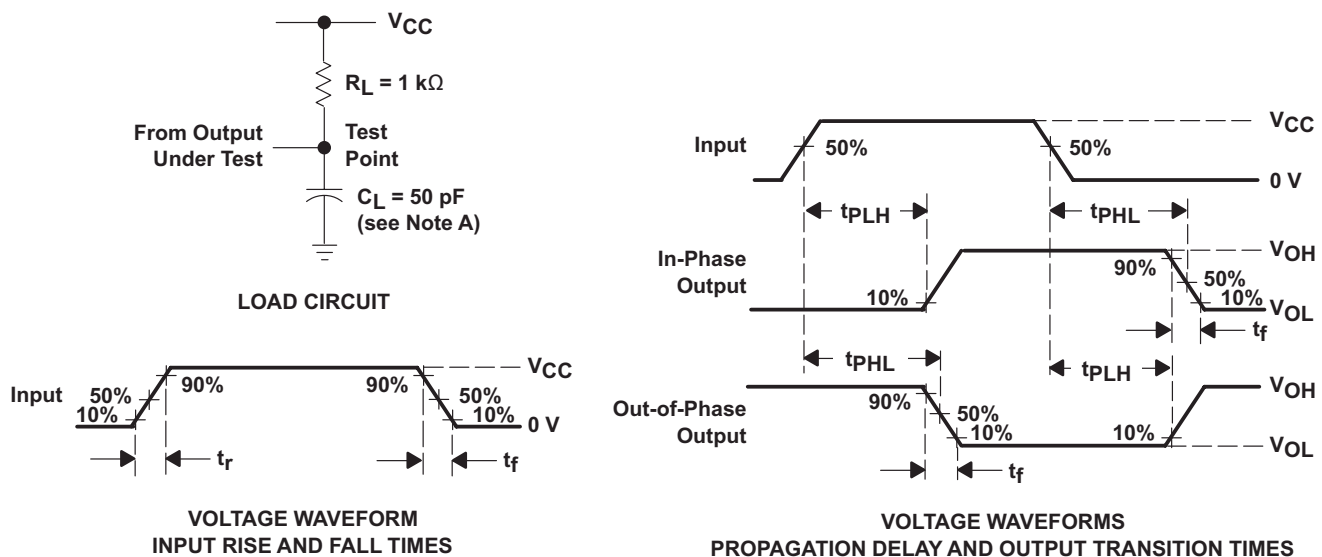
T<sub>A</sub> = 25°C

| PARAMETER       | TEST CONDITIONS                                       | TYP | UNIT |
|-----------------|-------------------------------------------------------|-----|------|
| C <sub>pd</sub> | Power dissipation capacitance per inverter<br>No load | 20  | pF   |

## 6.8 Typical Characteristics



## 7 Parameter Measurement Information



- $C_L$  includes probe and test-fixture capacitance.
- Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1$  MHz,  $Z_O = 50 \Omega$ ,  $t_r = 6$  ns,  $t_f = 6$  ns.
- The outputs are measured one at a time with one input transition per measurement.

**Figure 3. Load Circuit and Voltage Waveforms**

## 8 Detailed Description

### 8.1 Overview

The SNx4HC05 devices contain six independent inverters. They perform the Boolean function  $Y = \bar{A}$  in positive logic. The open-drain outputs require pullup resistors to perform correctly. They may be connected to other open-drain outputs to implement active-low wired-OR or active-high wired-AND functions.

### 8.2 Functional Block Diagram



**Figure 4. Logic Diagram (Positive Logic)**

### 8.3 Feature Description

The device's wide operating range allows it to be used in a variety of systems that use different logic levels. The strong current-sinking outputs allow the device to drive medium loads without significant increases in output voltage. In addition, the low power consumption makes this device a good choice for portable and battery power-sensitive applications.

### 8.4 Device Functional Modes

**Table 1. Function Table  
(Each Inverter)**

| INPUT A | OUTPUT Y |
|---------|----------|
| H       | L        |
| L       | H        |

## 9 Application and Implementation

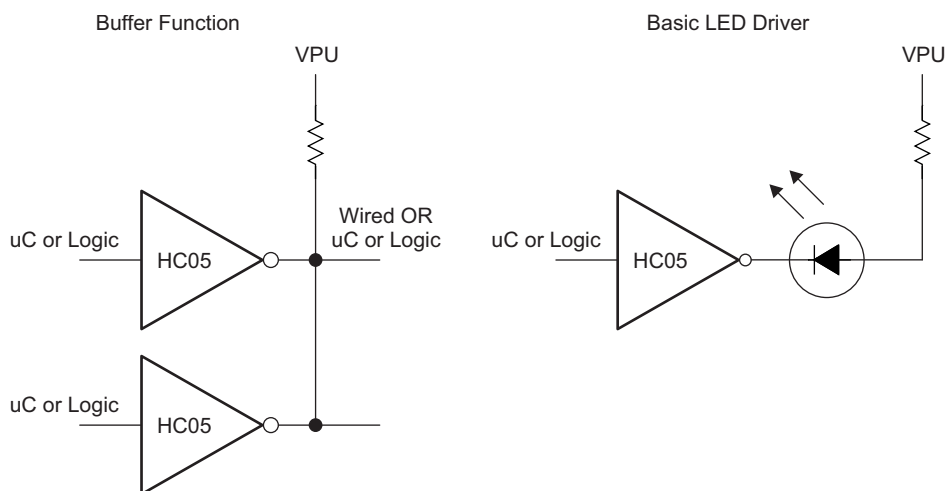
### NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

### 9.1 Application Information

The SN74HC05 device is a low drive open-drain CMOS device that can be used for a multitude of buffer type functions. The open-drain output can be pulled to any voltage between GND and  $V_{CC}$  making them ideal for down translation.

### 9.2 Typical Application



**Figure 5. Simplified Application Schematic**

#### 9.2.1 Design Requirements

This device uses CMOS technology and is open-drain so it has low-output drive only. Take care to avoid bus contention because it can drive currents that would exceed maximum limits. Parallel output drive can create fast edges into light loads so consider routing and load conditions to prevent ringing.

#### 9.2.2 Detailed Design Procedure

- Recommended input conditions:
  - Rise time and fall time specs see  $(\Delta t/\Delta V)$  in [Recommended Operating Conditions](#).
  - Specified high and low levels. See  $(V_{IH}$  and  $V_{IL})$  in [Recommended Operating Conditions](#).
- Recommended output conditions:
  - Load currents should not exceed 25 mA per output and 50 mA total for the part.



## Typical Application (continued)

### 9.2.3 Application Curve

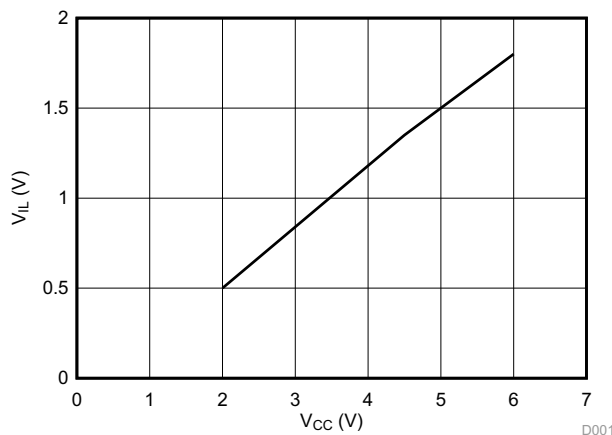


Figure 6. Max  $V_{IL}$  vs.  $V_{CC}$  Level

## 10 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the [Recommended Operating Conditions](#). Each  $V_{CC}$  terminal should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, TI recommends a 0.1- $\mu$ F capacitor. If there are multiple  $V_{CC}$  terminals, then TI recommends a 0.01- $\mu$ F or 0.022- $\mu$ F capacitor for each power terminal. Multiple bypass capacitors can be paralleled to reject different frequencies of noise. Frequencies of 0.1  $\mu$ F and 1  $\mu$ F are commonly used in parallel. The bypass capacitor should be installed as close as possible to the power terminal for best results.

## 11 Layout

### 11.1 Layout Guidelines

When using multiple bit logic devices, inputs should never float. In many cases, functions or parts of functions of digital logic devices are unused, for example, when only two inputs of a triple-input AND gate are used or only three of the four buffer gates are used. Such input pins should not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that should be applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or  $V_{CC}$  whichever makes more sense or is more convenient. Floating outputs is generally acceptable, unless the part is a transceiver.

### 11.2 Layout Example

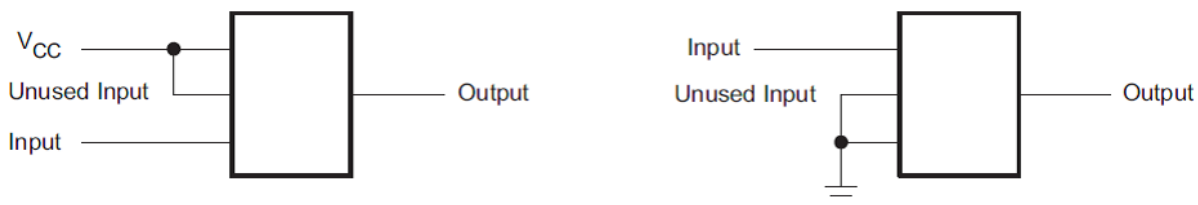


Figure 7. Layout Recommendation

## 12 Device and Documentation Support

### 12.1 Documentation Support

#### 12.1.1 Related Documentation

For related documentation see the following:

*Implications of Slow or Floating CMOS Inputs*, [SCBA004](#)

### 12.2 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

**Table 2. Related Links**

| PARTS    | PRODUCT FOLDER             | SAMPLE & BUY               | TECHNICAL DOCUMENTS        | TOOLS & SOFTWARE           | SUPPORT & COMMUNITY        |
|----------|----------------------------|----------------------------|----------------------------|----------------------------|----------------------------|
| SN54HC05 | <a href="#">Click here</a> | <a href="#">Click here</a> | <a href="#">Click here</a> | <a href="#">Click here</a> | <a href="#">Click here</a> |
| SN74HC05 | <a href="#">Click here</a> | <a href="#">Click here</a> | <a href="#">Click here</a> | <a href="#">Click here</a> | <a href="#">Click here</a> |

### 12.3 Trademarks

All trademarks are the property of their respective owners.

### 12.4 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

### 12.5 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

## 13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

**PACKAGING INFORMATION**

| Orderable Device | Status<br>(1) | Package Type | Package<br>Drawing | Pins | Package<br>Qty | Eco Plan<br>(2)            | Lead/Ball Finish<br>(6) | MSL Peak Temp<br>(3) | Op Temp (°C) | Device Marking<br>(4/5)               | Samples                 |
|------------------|---------------|--------------|--------------------|------|----------------|----------------------------|-------------------------|----------------------|--------------|---------------------------------------|-------------------------|
| 5962-88718012A   | ACTIVE        | LCCC         | FK                 | 20   | 1              | TBD                        | POST-PLATE              | N / A for Pkg Type   | -55 to 125   | 5962-<br>88718012A<br>SNJ54HC<br>05FK | <a href="#">Samples</a> |
| 5962-8871801CA   | ACTIVE        | CDIP         | J                  | 14   | 1              | TBD                        | A42                     | N / A for Pkg Type   | -55 to 125   | 5962-8871801CA<br>SNJ54HC05J          | <a href="#">Samples</a> |
| SN54HC05J        | ACTIVE        | CDIP         | J                  | 14   | 1              | TBD                        | A42                     | N / A for Pkg Type   | -55 to 125   | SN54HC05J                             | <a href="#">Samples</a> |
| SN74HC05D        | ACTIVE        | SOIC         | D                  | 14   | 50             | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | -40 to 125   | HC05                                  | <a href="#">Samples</a> |
| SN74HC05DE4      | ACTIVE        | SOIC         | D                  | 14   | 50             | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | -40 to 125   | HC05                                  | <a href="#">Samples</a> |
| SN74HC05DG4      | ACTIVE        | SOIC         | D                  | 14   | 50             | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | -40 to 125   | HC05                                  | <a href="#">Samples</a> |
| SN74HC05DR       | ACTIVE        | SOIC         | D                  | 14   | 2500           | Green (RoHS<br>& no Sb/Br) | CU NIPDAU   CU SN       | Level-1-260C-UNLIM   | -40 to 125   | HC05                                  | <a href="#">Samples</a> |
| SN74HC05DRE4     | ACTIVE        | SOIC         | D                  | 14   | 2500           | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | -40 to 125   | HC05                                  | <a href="#">Samples</a> |
| SN74HC05DRG4     | ACTIVE        | SOIC         | D                  | 14   | 2500           | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | -40 to 125   | HC05                                  | <a href="#">Samples</a> |
| SN74HC05DT       | ACTIVE        | SOIC         | D                  | 14   | 250            | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | -40 to 125   | HC05                                  | <a href="#">Samples</a> |
| SN74HC05DTG4     | ACTIVE        | SOIC         | D                  | 14   | 250            | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | -40 to 125   | HC05                                  | <a href="#">Samples</a> |
| SN74HC05N        | ACTIVE        | PDIP         | N                  | 14   | 25             | Pb-Free<br>(RoHS)          | CU NIPDAU               | N / A for Pkg Type   | -40 to 125   | SN74HC05N                             | <a href="#">Samples</a> |
| SN74HC05N3       | OBSOLETE      | PDIP         | N                  | 14   |                | TBD                        | Call TI                 | Call TI              | -40 to 85    |                                       |                         |
| SN74HC05NE4      | ACTIVE        | PDIP         | N                  | 14   | 25             | Pb-Free<br>(RoHS)          | CU NIPDAU               | N / A for Pkg Type   | -40 to 125   | SN74HC05N                             | <a href="#">Samples</a> |
| SN74HC05NSR      | ACTIVE        | SO           | NS                 | 14   | 2000           | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | -40 to 125   | HC05                                  | <a href="#">Samples</a> |
| SN74HC05NSRE4    | ACTIVE        | SO           | NS                 | 14   | 2000           | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | -40 to 125   | HC05                                  | <a href="#">Samples</a> |
| SN74HC05NSRG4    | ACTIVE        | SO           | NS                 | 14   | 2000           | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | -40 to 125   | HC05                                  | <a href="#">Samples</a> |

| Orderable Device | Status<br>(1) | Package Type | Package<br>Drawing | Pins | Package<br>Qty | Eco Plan<br>(2)            | Lead/Ball Finish<br>(6) | MSL Peak Temp<br>(3) | Op Temp (°C) | Device Marking<br>(4/5)               | Samples                 |
|------------------|---------------|--------------|--------------------|------|----------------|----------------------------|-------------------------|----------------------|--------------|---------------------------------------|-------------------------|
| SN74HC05PWR      | ACTIVE        | TSSOP        | PW                 | 14   | 2000           | Green (RoHS<br>& no Sb/Br) | CU NIPDAU   CU SN       | Level-1-260C-UNLIM   | -40 to 125   | HC05                                  | <a href="#">Samples</a> |
| SN74HC05PWRG4    | ACTIVE        | TSSOP        | PW                 | 14   | 2000           | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | -40 to 125   | HC05                                  | <a href="#">Samples</a> |
| SN74HC05PWT      | ACTIVE        | TSSOP        | PW                 | 14   | 250            | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | -40 to 125   | HC05                                  | <a href="#">Samples</a> |
| SN74HC05PWTG4    | ACTIVE        | TSSOP        | PW                 | 14   | 250            | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | -40 to 125   | HC05                                  | <a href="#">Samples</a> |
| SNJ54HC05FK      | ACTIVE        | LCCC         | FK                 | 20   | 1              | TBD                        | POST-PLATE              | N / A for Pkg Type   | -55 to 125   | 5962-<br>88718012A<br>SNJ54HC<br>05FK | <a href="#">Samples</a> |
| SNJ54HC05J       | ACTIVE        | CDIP         | J                  | 14   | 1              | TBD                        | A42                     | N / A for Pkg Type   | -55 to 125   | 5962-8871801CA<br>SNJ54HC05J          | <a href="#">Samples</a> |

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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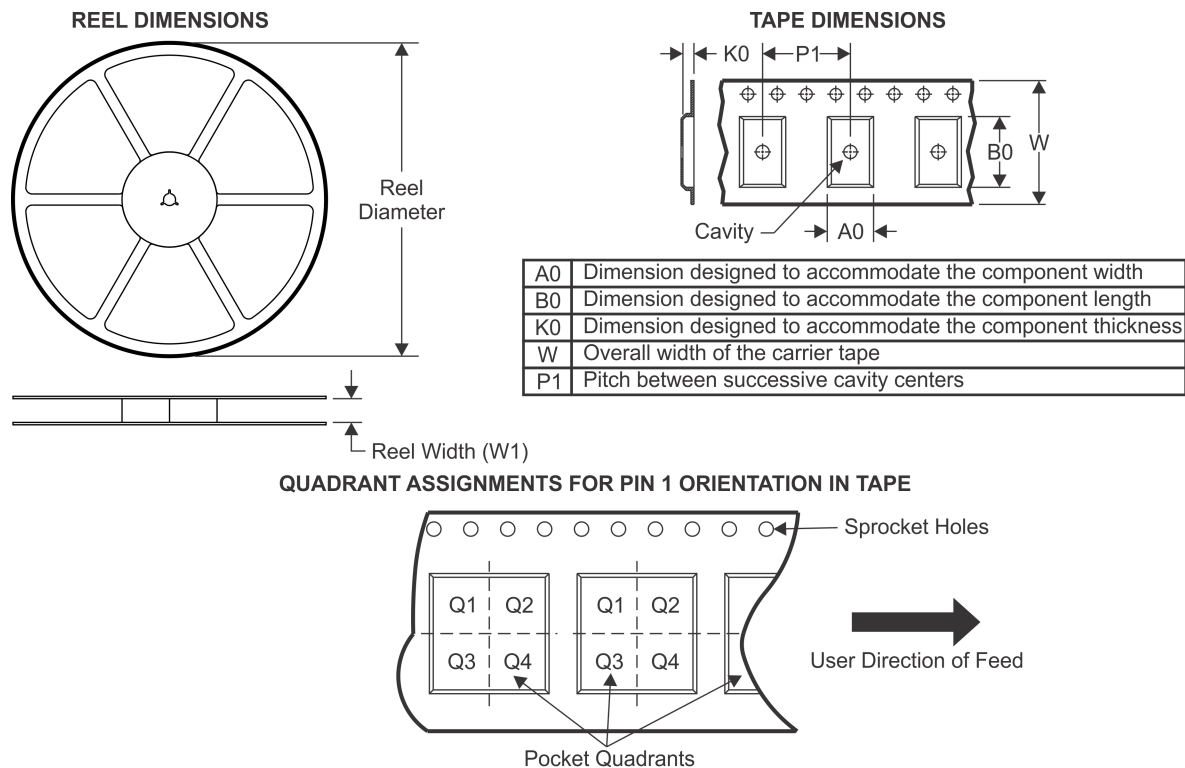
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**OTHER QUALIFIED VERSIONS OF SN54HC05, SN74HC05 :**

- Catalog: [SN74HC05](#)
- Military: [SN54HC05](#)

NOTE: Qualified Version Definitions:

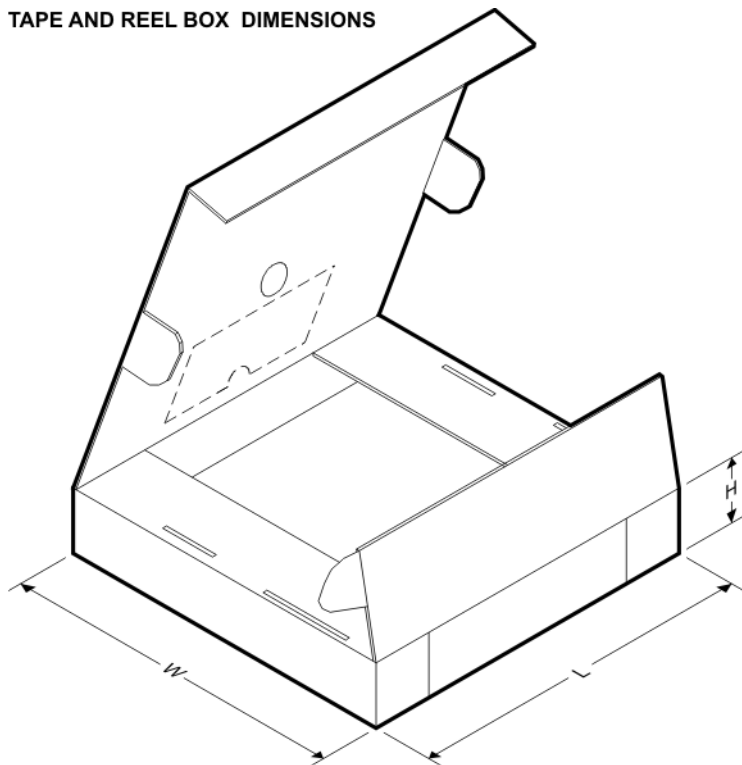
- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

**TAPE AND REEL INFORMATION**


\*All dimensions are nominal

| Device        | Package Type | Package Drawing | Pins | SPQ  | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|---------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SN74HC05DR    | SOIC         | D               | 14   | 2500 | 330.0              | 16.4               | 6.5     | 9.0     | 2.1     | 8.0     | 16.0   | Q1            |
| SN74HC05DR    | SOIC         | D               | 14   | 2500 | 330.0              | 16.4               | 6.5     | 9.0     | 2.1     | 8.0     | 16.0   | Q1            |
| SN74HC05DR    | SOIC         | D               | 14   | 2500 | 330.0              | 16.8               | 6.5     | 9.5     | 2.3     | 8.0     | 16.0   | Q1            |
| SN74HC05DRG4  | SOIC         | D               | 14   | 2500 | 330.0              | 16.4               | 6.5     | 9.0     | 2.1     | 8.0     | 16.0   | Q1            |
| SN74HC05DRG4  | SOIC         | D               | 14   | 2500 | 330.0              | 16.4               | 6.5     | 9.0     | 2.1     | 8.0     | 16.0   | Q1            |
| SN74HC05DT    | SOIC         | D               | 14   | 250  | 330.0              | 16.4               | 6.5     | 9.0     | 2.1     | 8.0     | 16.0   | Q1            |
| SN74HC05NSR   | SO           | NS              | 14   | 2000 | 330.0              | 16.4               | 8.2     | 10.5    | 2.5     | 12.0    | 16.0   | Q1            |
| SN74HC05PWR   | TSSOP        | PW              | 14   | 2000 | 330.0              | 12.4               | 6.9     | 5.6     | 1.6     | 8.0     | 12.0   | Q1            |
| SN74HC05PWR   | TSSOP        | PW              | 14   | 2000 | 330.0              | 12.4               | 6.9     | 5.6     | 1.6     | 8.0     | 12.0   | Q1            |
| SN74HC05PWRG4 | TSSOP        | PW              | 14   | 2000 | 330.0              | 12.4               | 6.9     | 5.6     | 1.6     | 8.0     | 12.0   | Q1            |
| SN74HC05PWT   | TSSOP        | PW              | 14   | 250  | 330.0              | 12.4               | 6.9     | 5.6     | 1.6     | 8.0     | 12.0   | Q1            |

## TAPE AND REEL BOX DIMENSIONS



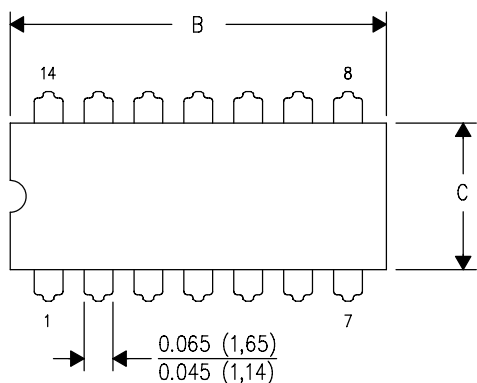
\*All dimensions are nominal

| Device        | Package Type | Package Drawing | Pins | SPQ  | Length (mm) | Width (mm) | Height (mm) |
|---------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN74HC05DR    | SOIC         | D               | 14   | 2500 | 367.0       | 367.0      | 38.0        |
| SN74HC05DR    | SOIC         | D               | 14   | 2500 | 333.2       | 345.9      | 28.6        |
| SN74HC05DR    | SOIC         | D               | 14   | 2500 | 364.0       | 364.0      | 27.0        |
| SN74HC05DRG4  | SOIC         | D               | 14   | 2500 | 367.0       | 367.0      | 38.0        |
| SN74HC05DRG4  | SOIC         | D               | 14   | 2500 | 333.2       | 345.9      | 28.6        |
| SN74HC05DT    | SOIC         | D               | 14   | 250  | 367.0       | 367.0      | 38.0        |
| SN74HC05NSR   | SO           | NS              | 14   | 2000 | 367.0       | 367.0      | 38.0        |
| SN74HC05PWR   | TSSOP        | PW              | 14   | 2000 | 364.0       | 364.0      | 27.0        |
| SN74HC05PWR   | TSSOP        | PW              | 14   | 2000 | 367.0       | 367.0      | 35.0        |
| SN74HC05PWRG4 | TSSOP        | PW              | 14   | 2000 | 367.0       | 367.0      | 35.0        |
| SN74HC05PWT   | TSSOP        | PW              | 14   | 250  | 367.0       | 367.0      | 35.0        |

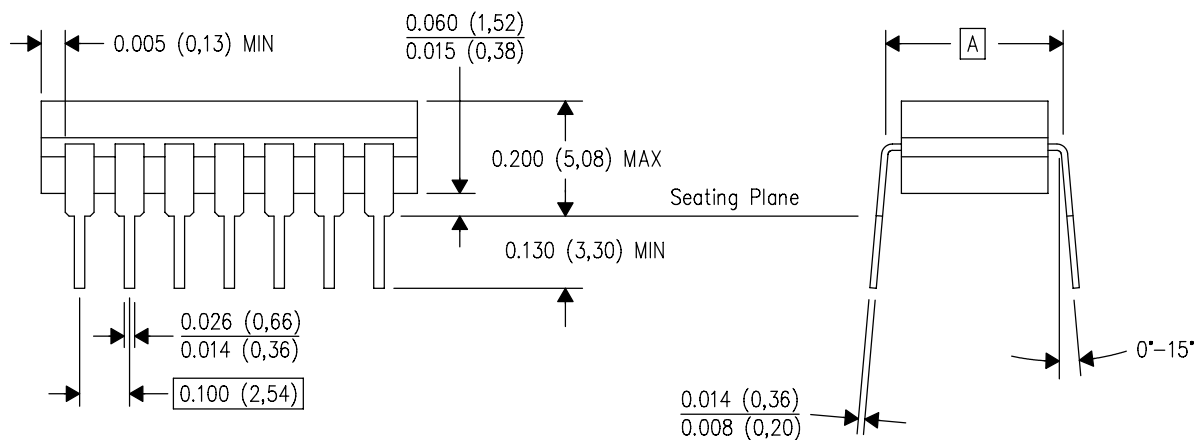
J (R-GDIP-T\*\*)

14 LEADS SHOWN

# CERAMIC DUAL IN-LINE PACKAGE



| PINS **<br>DIM | 14                     | 16                     | 18                     | 20                     |
|----------------|------------------------|------------------------|------------------------|------------------------|
| A              | 0.300<br>(7,62)<br>BSC | 0.300<br>(7,62)<br>BSC | 0.300<br>(7,62)<br>BSC | 0.300<br>(7,62)<br>BSC |
| B MAX          | 0.785<br>(19,94)       | .840<br>(21,34)        | 0.960<br>(24,38)       | 1.060<br>(26,92)       |
| B MIN          | —                      | —                      | —                      | —                      |
| C MAX          | 0.300<br>(7,62)        | 0.300<br>(7,62)        | 0.310<br>(7,87)        | 0.300<br>(7,62)        |
| C MIN          | 0.245<br>(6,22)        | 0.245<br>(6,22)        | 0.220<br>(5,59)        | 0.245<br>(6,22)        |



4040083/F 03/03

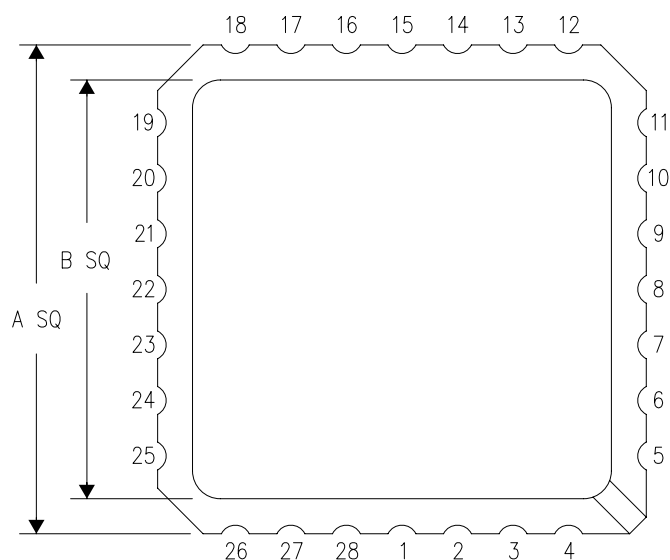
- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package is hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.



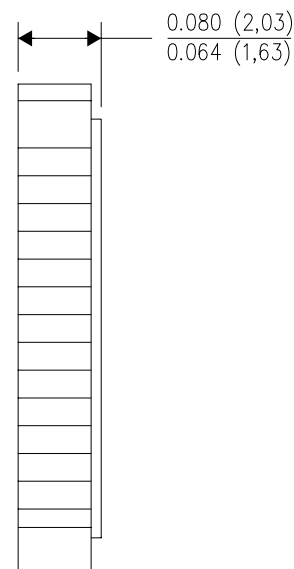
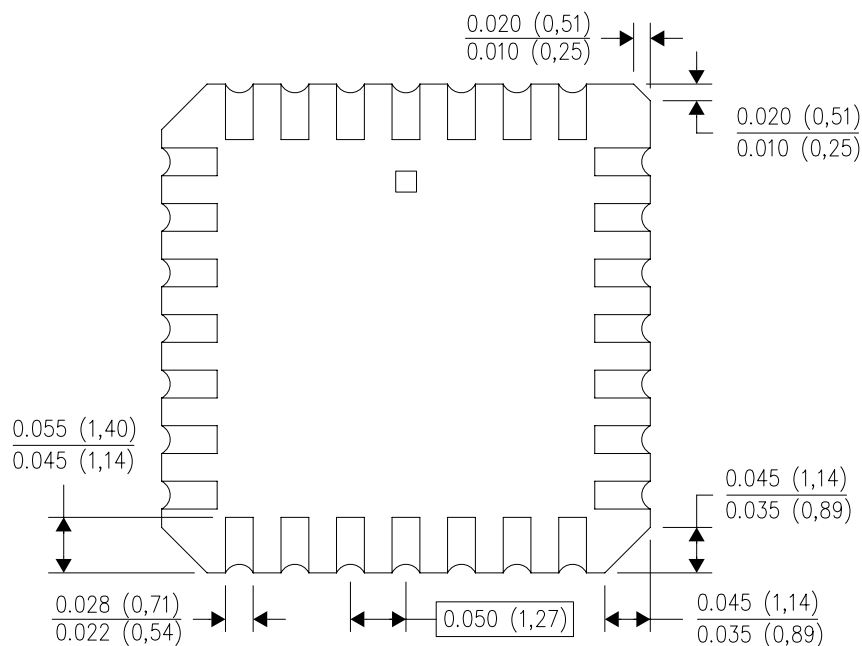
FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



| NO. OF<br>TERMINALS<br>** | A                |                  | B                |                  |
|---------------------------|------------------|------------------|------------------|------------------|
|                           | MIN              | MAX              | MIN              | MAX              |
| 20                        | 0.342<br>(8,69)  | 0.358<br>(9,09)  | 0.307<br>(7,80)  | 0.358<br>(9,09)  |
| 28                        | 0.442<br>(11,23) | 0.458<br>(11,63) | 0.406<br>(10,31) | 0.458<br>(11,63) |
| 44                        | 0.640<br>(16,26) | 0.660<br>(16,76) | 0.495<br>(12,58) | 0.560<br>(14,22) |
| 52                        | 0.740<br>(18,78) | 0.761<br>(19,32) | 0.495<br>(12,58) | 0.560<br>(14,22) |
| 68                        | 0.938<br>(23,83) | 0.962<br>(24,43) | 0.850<br>(21,6)  | 0.858<br>(21,8)  |
| 84                        | 1.141<br>(28,99) | 1.165<br>(29,59) | 1.047<br>(26,6)  | 1.063<br>(27,0)  |



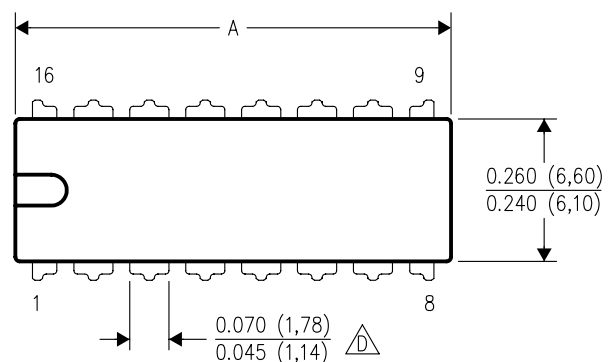
4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package can be hermetically sealed with a metal lid.
  - Falls within JEDEC MS-004

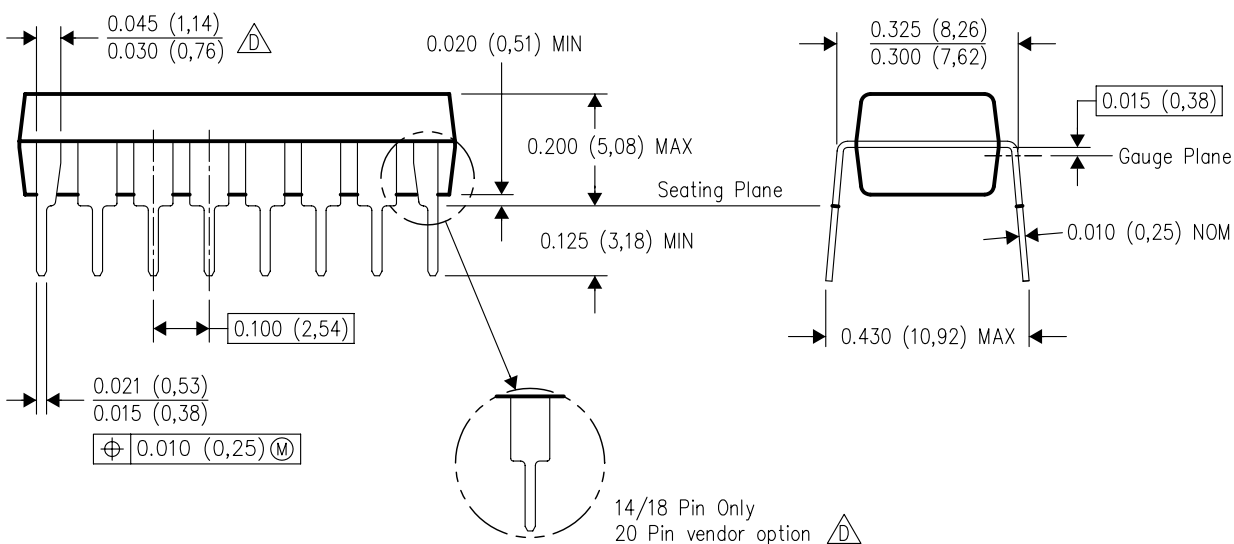
N (R-PDIP-T\*\*)

16 PINS SHOWN

## PLASTIC DUAL-IN-LINE PACKAGE



| PINS **<br>DIM      | 14               | 16               | 18               | 20               |
|---------------------|------------------|------------------|------------------|------------------|
| A MAX               | 0.775<br>(19,69) | 0.775<br>(19,69) | 0.920<br>(23,37) | 1.060<br>(26,92) |
| A MIN               | 0.745<br>(18,92) | 0.745<br>(18,92) | 0.850<br>(21,59) | 0.940<br>(23,88) |
| MS-001<br>VARIATION | AA               | BB               | AC               | AD               |

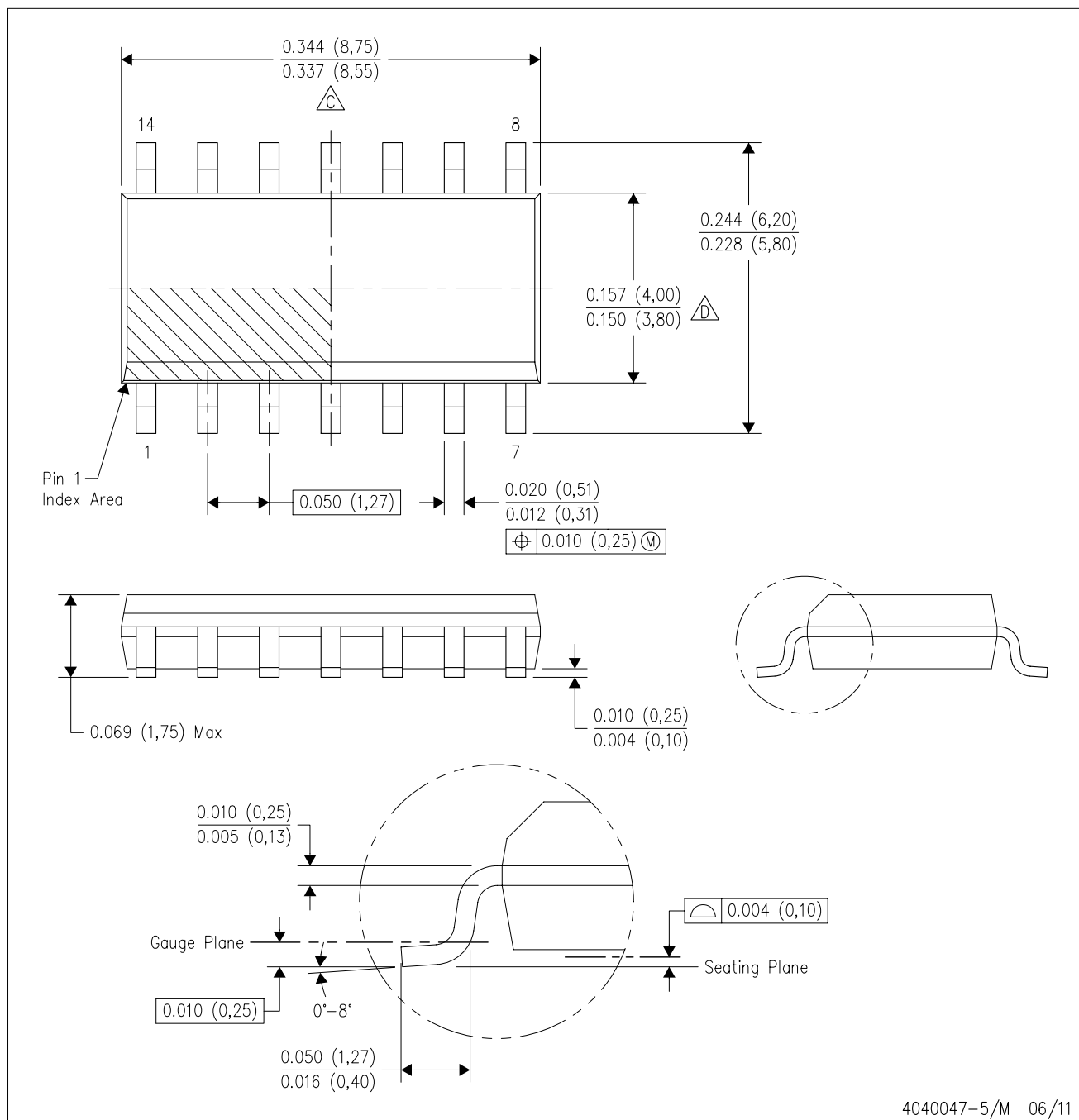


4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  -  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  -  The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE

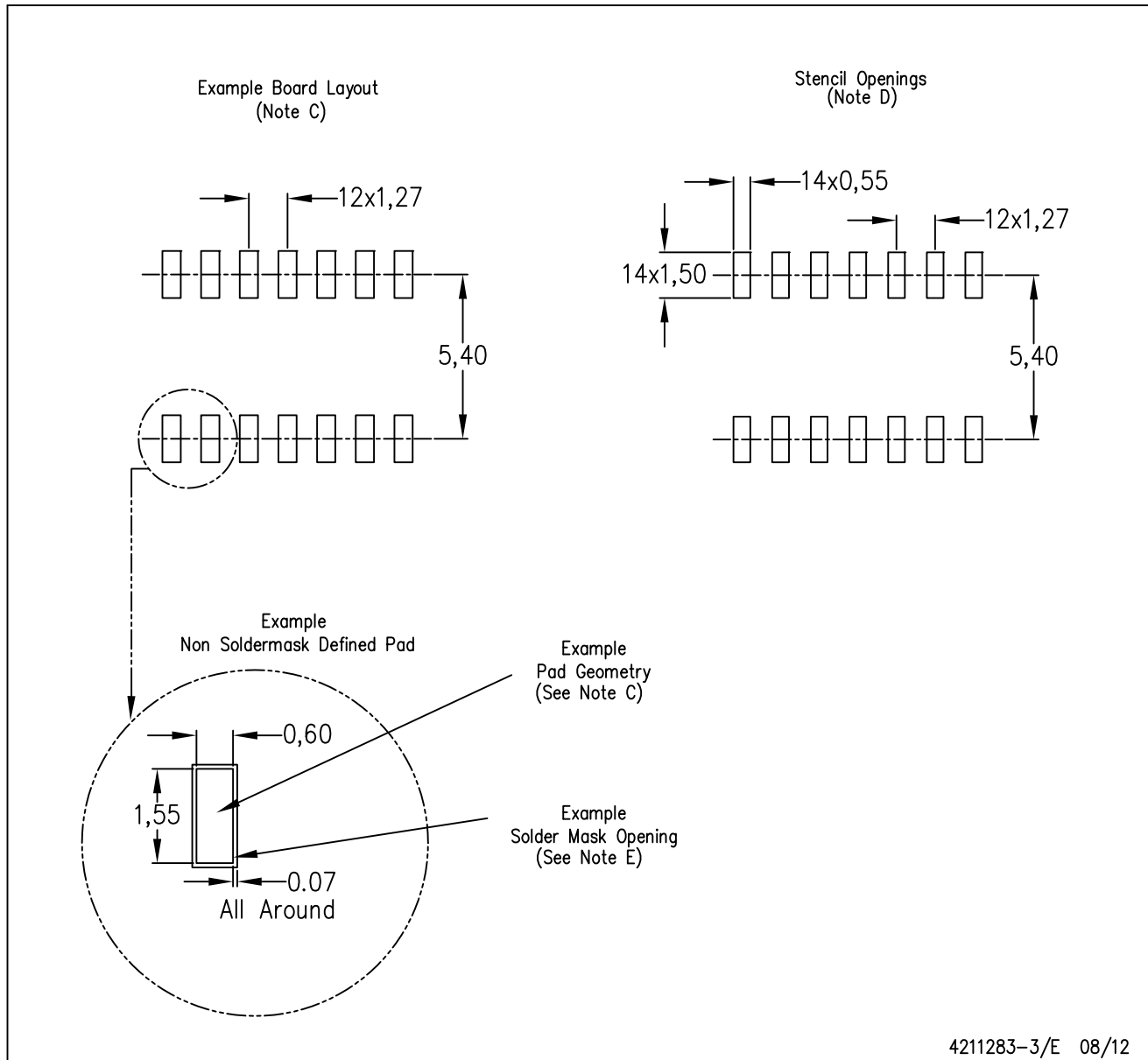


NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE

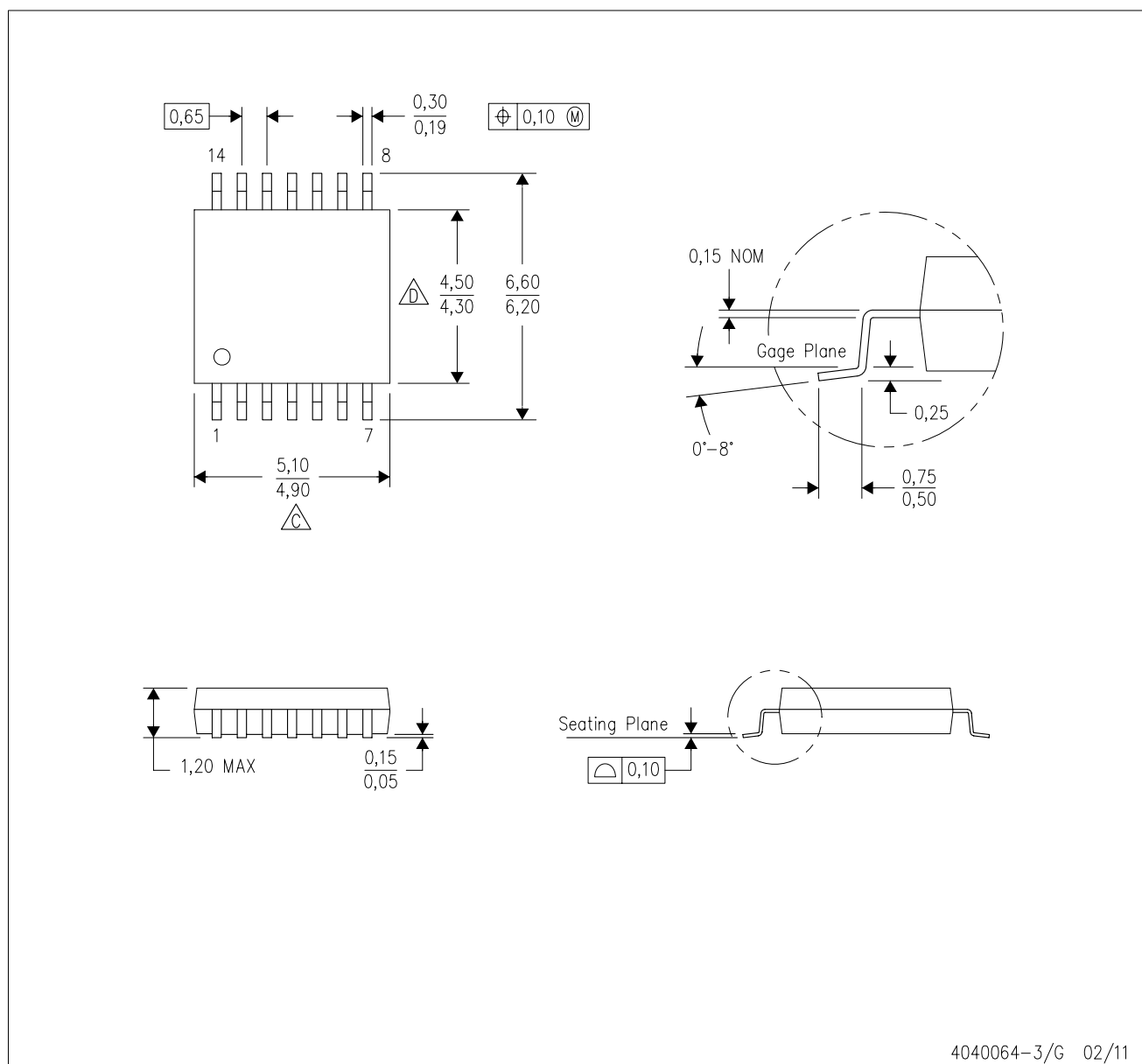


4211283-3/E 08/12

- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G14)

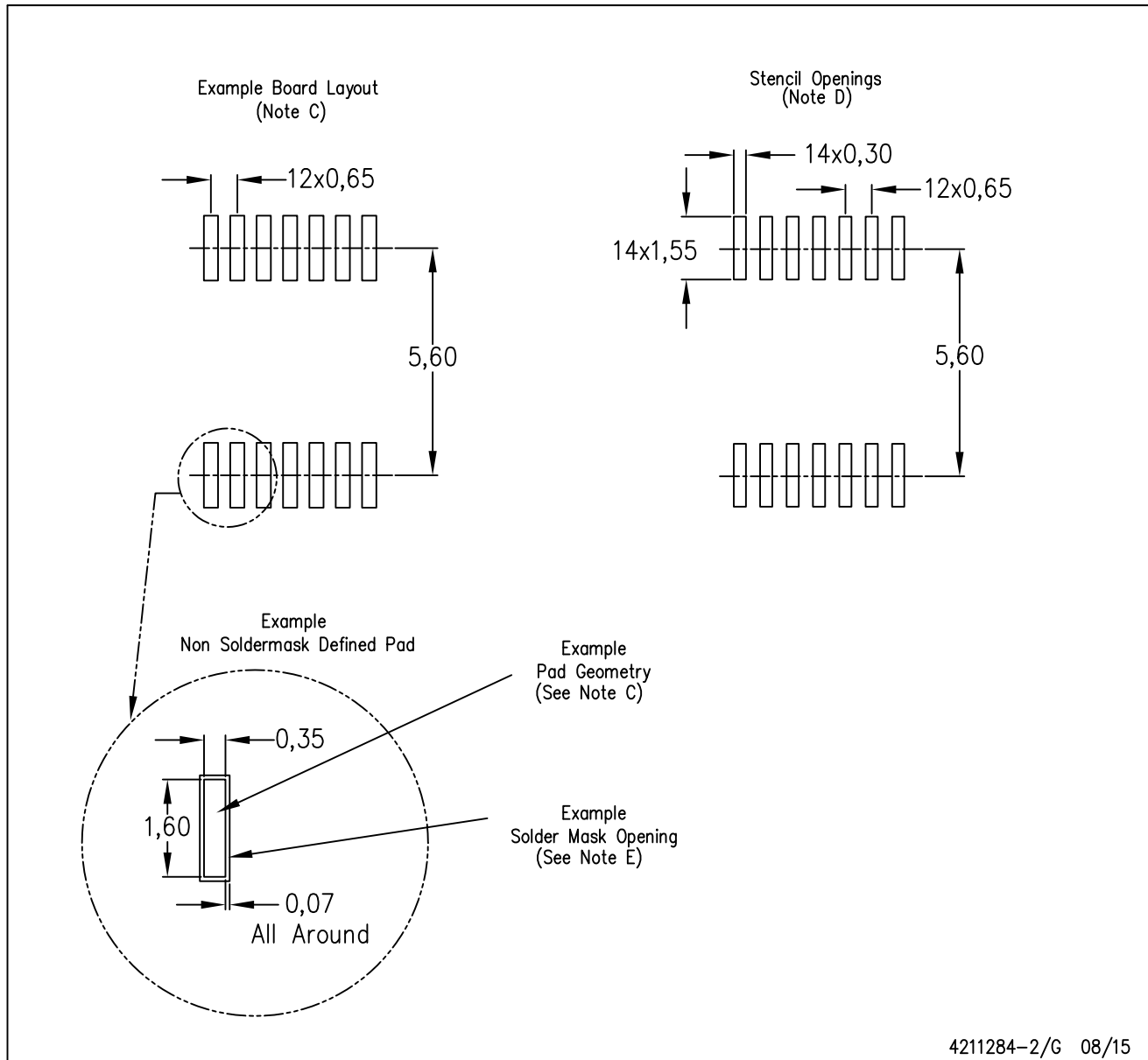
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
  - E. Falls within JEDEC MO-153

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



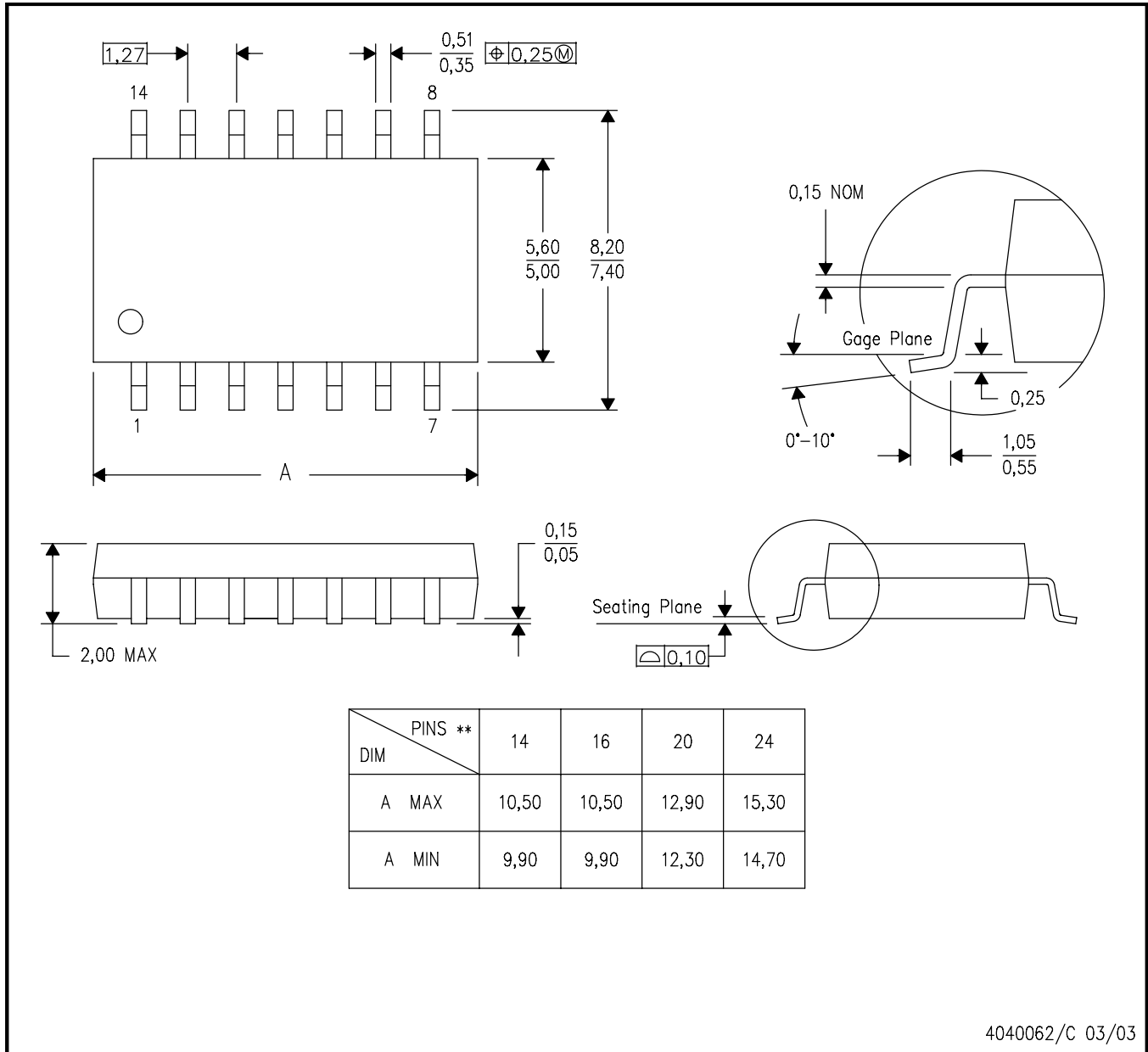
- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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| OMAP Applications Processors | <a href="http://www.ti.com/omap">www.ti.com/omap</a>                                 |
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| Communications and Telecom    | <a href="http://www.ti.com/communications">www.ti.com/communications</a>                 |
| Computers and Peripherals     | <a href="http://www.ti.com/computers">www.ti.com/computers</a>                           |
| Consumer Electronics          | <a href="http://www.ti.com/consumer-apps">www.ti.com/consumer-apps</a>                   |
| Energy and Lighting           | <a href="http://www.ti.com/energy">www.ti.com/energy</a>                                 |
| Industrial                    | <a href="http://www.ti.com/industrial">www.ti.com/industrial</a>                         |
| Medical                       | <a href="http://www.ti.com/medical">www.ti.com/medical</a>                               |
| Security                      | <a href="http://www.ti.com/security">www.ti.com/security</a>                             |
| Space, Avionics and Defense   | <a href="http://www.ti.com/space-avionics-defense">www.ti.com/space-avionics-defense</a> |
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